

Automating Experiments Using Charged Particle Beam Nanofabrication Tools

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Motivation

Automated deterministic placement of single defect emitters in a wide range of materials, including 2D materials

Currently broad beam implantation is used, which lacks

- Positioning precision
- Active center yield
- Spot size and number of ions in a single spot
- Implant verification
- Requires an anneal

Approach

We propose to use automated low energy retarding implantation and utilize the following

Implantation into (2D) materials with ultra-low ion energy

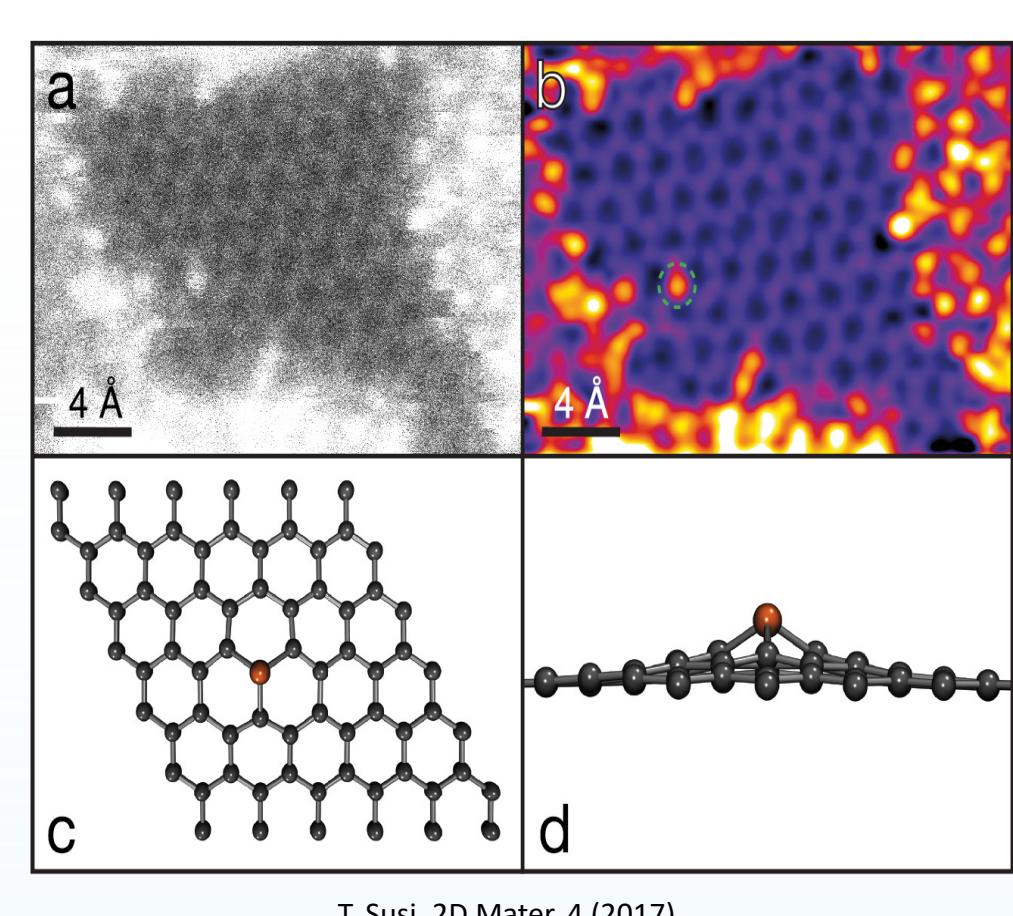
- Example: 30 eV for P in Graphene

Develop low-energy focused ion beam (FIB) implanters

- Ex: Photonics requires sub-wavelength positioning accuracy

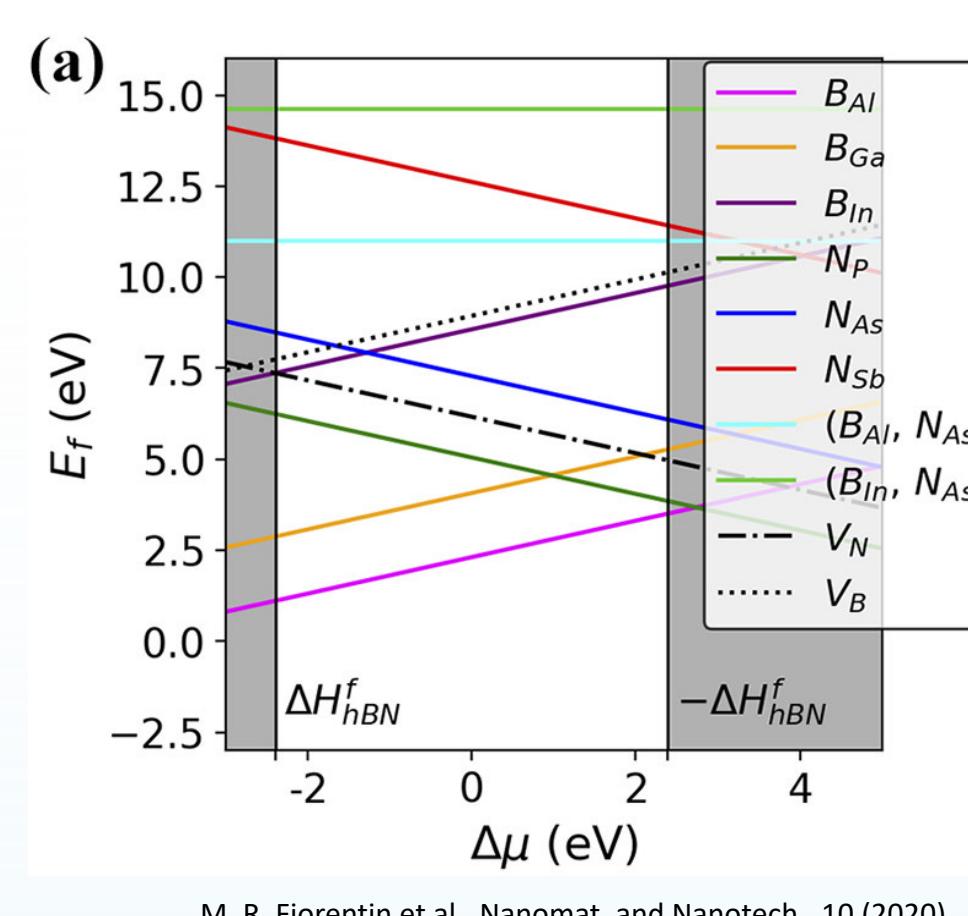
FIBs are in keV energy range with 10-100 nm-spot sizes

- Use biased sample holder to make <100 eV on-target



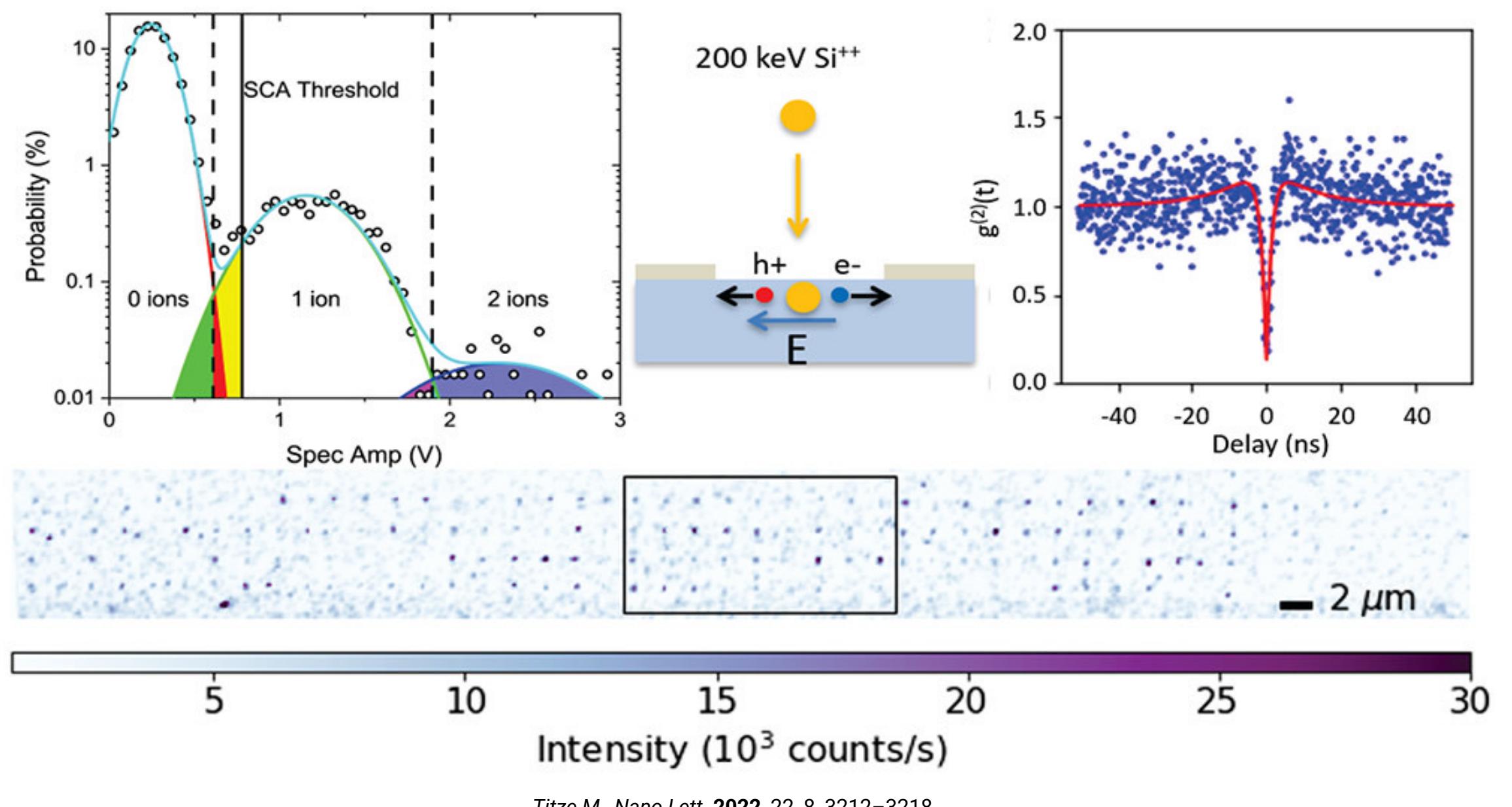
Our approach involves the Raith Velion, Zeiss Orion Plus, and A&D Nanolmpalnter FIBs to

- Implant single low energy ions (5 – 200 keV)
- Control positioning and implant spot size
- Validate implants with in-situ characterization methods
- Feedback errors to operator



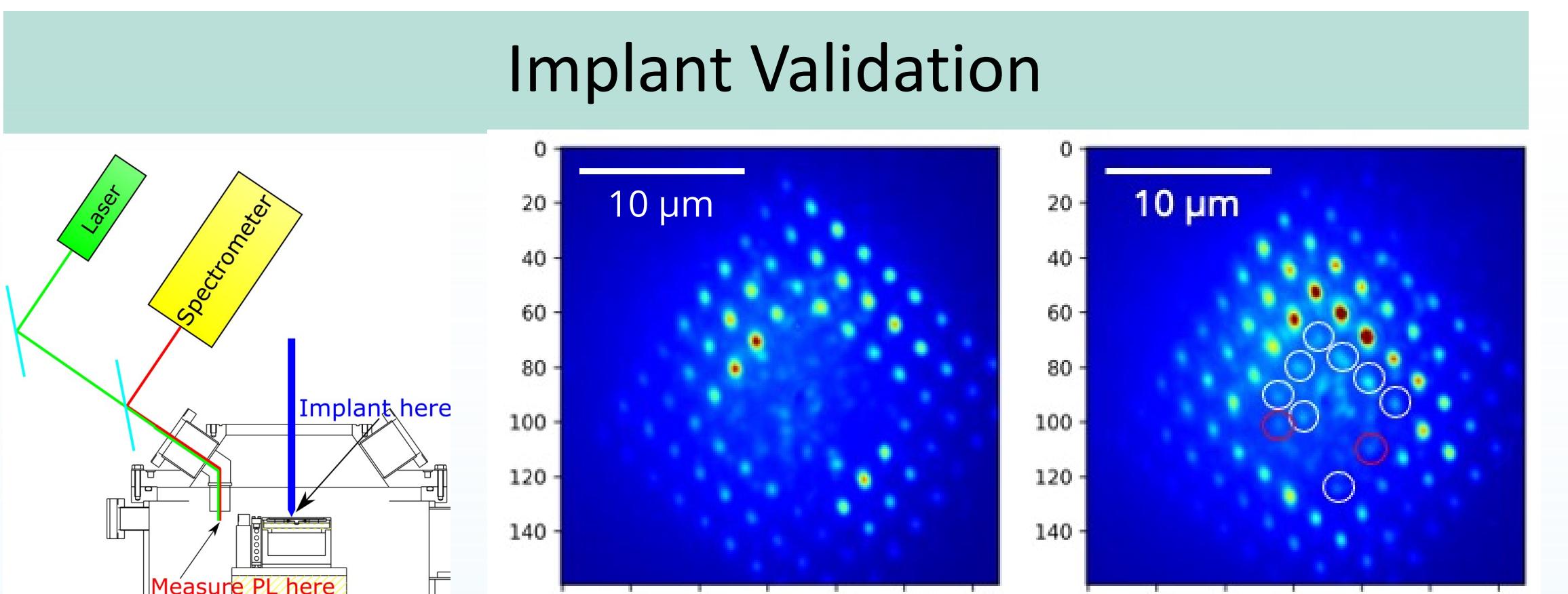
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Single SiV in Diamond Manufacturing



In-situ counted ion implantation for arrays of single silicon vacancy (SiV) defects

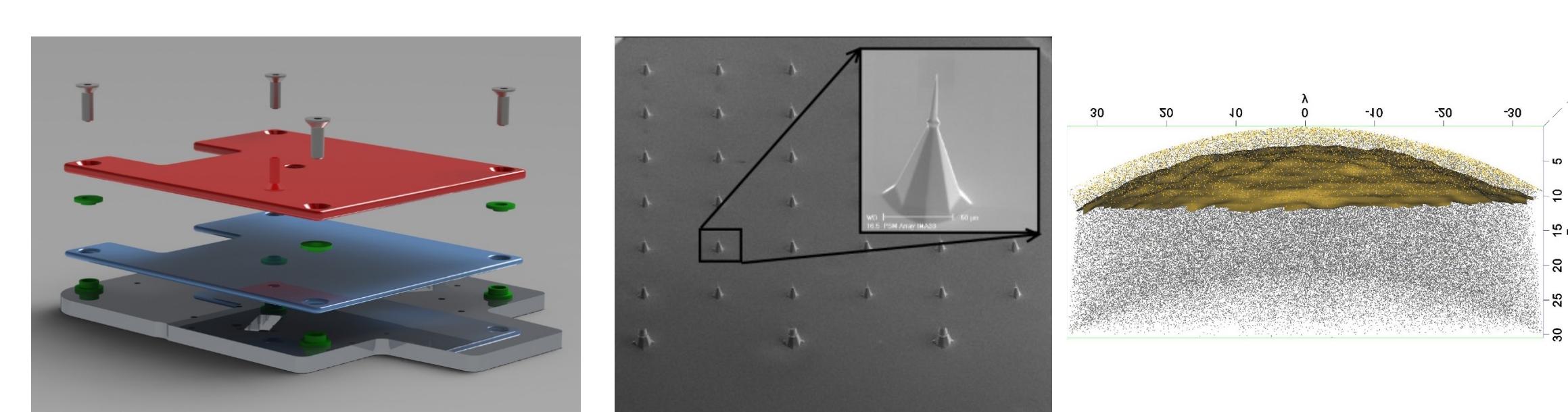
- In-situ detection measures implanted ions with a 2-fold improvement of the implant error to form a single SiV compared to timed implantation
- 7-fold improvement compared to timed implantation, with 2.98% SiV yield
- Hanbury–Brown–Twiss interferometry confirms 82% single photon emitters



SiV in SiC do not require high-temperature annealing to activate

- Measure background PL
- Implant
- Measure PL
- (Re)Implant locations that do not have PL

Low Energy Implants



Using a biased sample holder design, 20 Angstrom deep 1 keV Au deposition, confirmed by Atom Probe Tomography

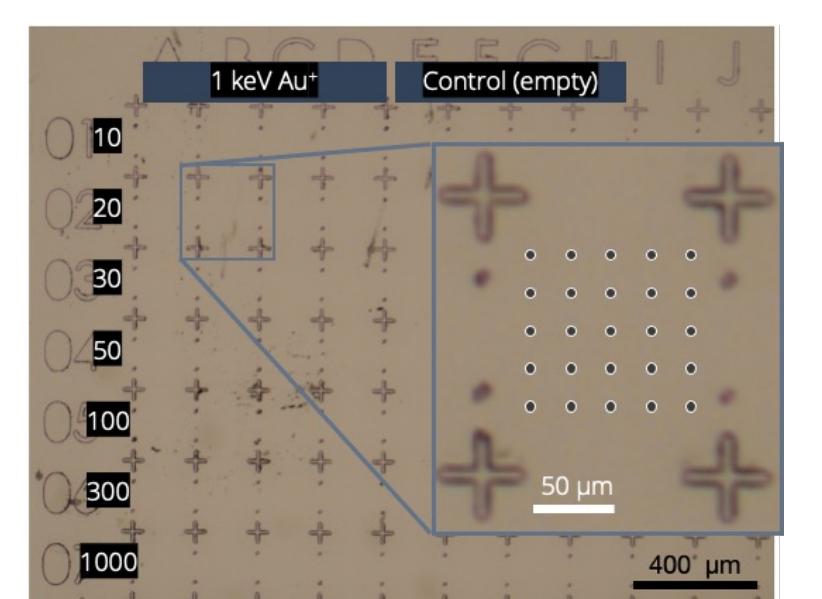
Ongoing efforts

- Lower energies
- Smaller spot sizes

Experiment Automation

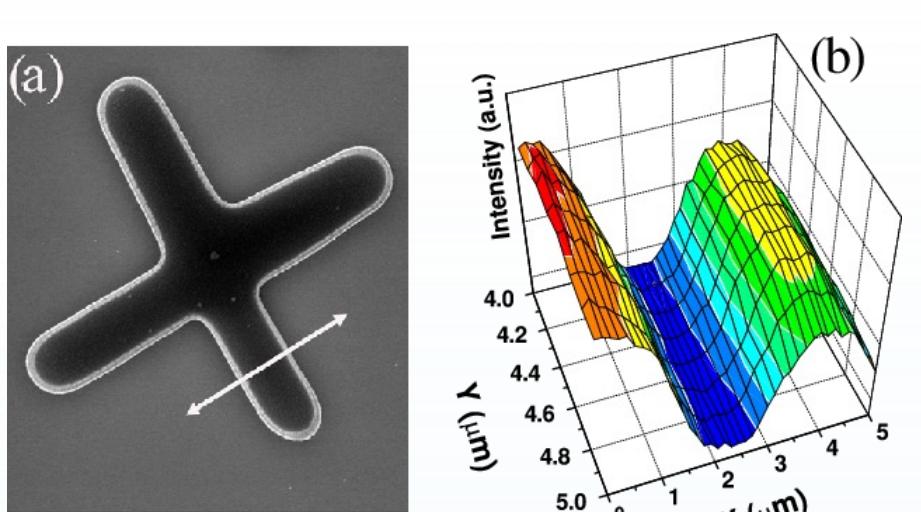
Designing samples for ease of navigation

- Alpha numeric sectors
- Global positioning marks
- Local alignment
- Realignment in-situ



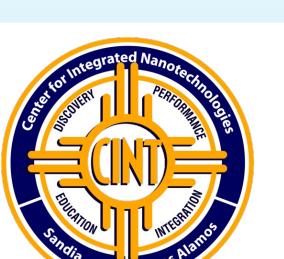
Automating position correction after the marker scan

- Rigid transformation with user input
- Automatic write-field alignment using marker intensity profiles



Automating column control

- Execute ion implant/mill at predefined points
- In-situ 2nd channel of information data capture (SEM, PL, etc.)
- ML Feature recognition (Canny edge, Hough)
- Implant/Mill validation
- Decision making feedback to repeat or move



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Atom Probe Tomography research was conducted as part of a user project at the Center for Nanophase Materials Sciences (CNMS), which is a US Department of Energy, Office of Science User Facility at Oak Ridge National Laboratory.

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